

DATASHEET

Technical Data Sheet Opto Interrupter ITR8307/S18/TR8

Features

- Fast response time
- High sensitivity
- Cut-Off visible wavelength
- Thin
- Compact
- Pb free
- This product itself will remain within RoHS compliant version.
- Compliance with EU REACH
- Compliance Halogen Free(Br < 900ppm, Cl < 900ppm, Br+Cl < 1500ppm)



Descriptions

<u>ITR8307/S18/TR8</u> is a light reflection switch which includes a GaAs IR-LED transmitter and a NPN photo-transistor with a high sensitive receiver for short distance, operating in the infrared range. Both components are mounted side- by- side in a plastic package.

Applications

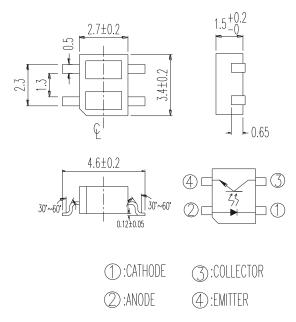
- Camera
- VCR
- Floppy disk driver
- Cassette type recorder
- Various microcomputer control equipment

Device Selection Guide

Device No.	Chip Material
IR	GaAs
PT	Silicon



Package Dimensions



Notes: 1.All dimensions are in millimeters

2.Tolerances unless dimensions ±0.15mm

Absolute Maximum Ratings (Ta=25°C)

			1	
	Parameter	Symbol	Rating	Unit
	Power Dissipation at(or below) 25°C Free Air Temperature	Pd	75	mW
Input	Reverse Voltage	V_R	5	V
	Forward Current	I_{F}	50	mA
	Peak Forward Current (*1)	I_{FP}	1	A
Output	Collector Power Dissipation	P_{C}	75	mW
	Collector Current	I_{C}	50	mA
	Collector-Emitter Voltage	B V _{CEO}	30	V
	Emitter-Collector Voltage	B V _{ECO}	5	V
Operating	Temperature	Topr	-25~+85	$^{\circ}\mathbb{C}$
Storage Temperature		Tstg	-30~+90	$^{\circ}\mathbb{C}$
Lead Soldering Temperature (*2)		Tsol	260	$^{\circ}\!\mathbb{C}$

Notes: (*1) tw=100 µsec., T=10 msec. (*2) t=5 Sec



Electro-Optical Characteristics (Ta=25°C)

Pa	arameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Input	Forward Voltage	V_{F}		1.2	1.6	V	I _F =20mA
	Reverse Current	I_R			10	μΑ	V _R =5V
	Peak Wavelength	$\lambda_{ m P}$		940		nm	
Output	Dark Current	ICEO			100	nA	V _{CE} =10 V
	C-E Saturation Voltage	V _{CE} (sat)			0.4	V	I _C =2mA ,Ee=1mW/cm ²
Transfer Characteristics	Light Current	I _{C(ON)}	0.3		0.8	mA	V _{CE} =5V I _F =20mA
	Leakage Current	I _{LEAK}			1	μΑ	$V_{CE}=5V$ $I_F=20mA$
	Rise time	$t_{\rm r}$	17.	20		μS	V_{CE} =2 V I_{C} =100 μ A R_{L} =1 $k\Omega$,
	Fall time	t_{f}		20		μS	

Rank

Conditions: $I_F=20mA$ $V_{CE}=5V$

Unit: µA

Bin number	Min	Max
В	300	600
С	500	800



Typical Electrical/Optical/Characteristics Curves for IR

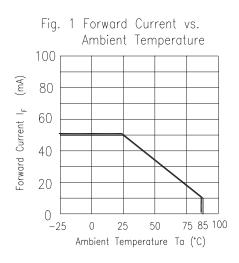


Fig. 3 Peak Emission Wavelength vs. Ambient Temperature

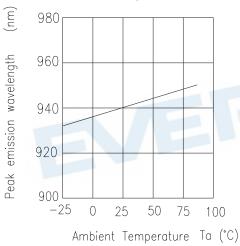


Fig. 5 Forward Voltage vs.

Ambient Temperature

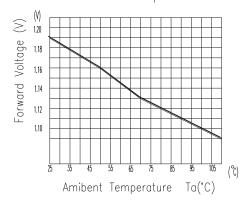


Fig. 2 Spectral Distribution

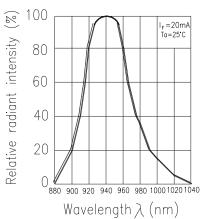


Fig. 4 Forward Current vs. Forward Voltage

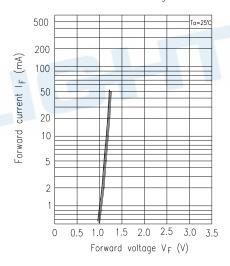
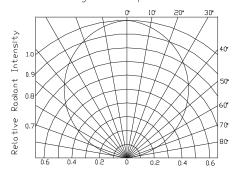


Fig. 6 Relative Radiant Intensity vs.

Angular Displacement





Typical Electro/Optical/Characteristics Curves for PT

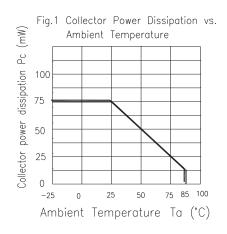
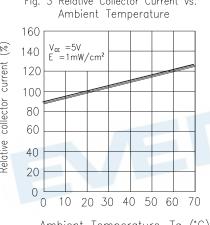


Fig. 3 Relative Collector Current vs. Ambient Temperature 160 8 140 =1mW/cm² Relative collector current 120 100 80 60 40 20 20 30 40 50 60 Ambient Temperature Ta (°C)



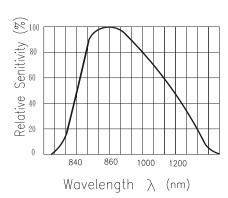
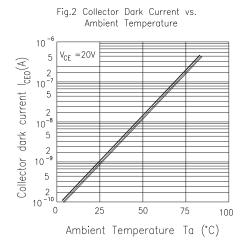
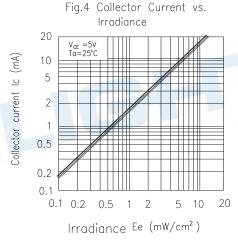
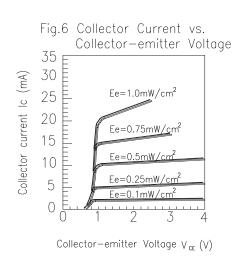


Fig.5 Spectral Sensitivity





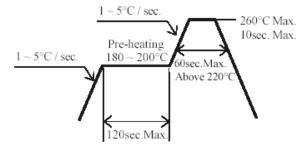




Recommended Method of Storage

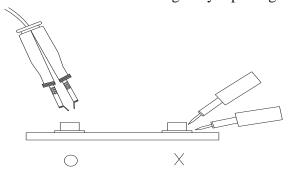
The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

- Shelf life in sealed bag: 12 months at < 40 °C and < 90% relative humidity (RH)
- After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
 - a) Mounted within 72 hours of factory conditions < 30 °C/60% RH, or
 - b) Stored at <20% RH
- Devices require bake, before mounting, if:
 Humidity Indicator Card is > 20% when read at 23 ± 5 °C
- If baking is required, devices may be baked:
 - a) 192 hours at 40°C, and <5% RH(dry air/nitrogen) or
 - b) 96 hours at 60°C, and <5% RH for all device containers
 - c) 24 hours at 125 °C
- Soldering Condition
 - a) Pb-free solder temperature profile



- b) Reflow soldering should not be done more than two times.
- c) When soldering, do not put stress on the Device during heating.
- d) After soldering, do not warp the circuit board.
- Repairing

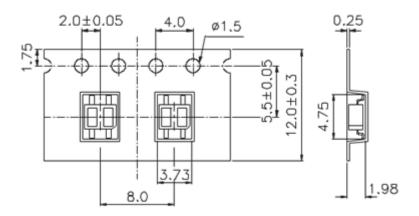
Repair should not be done after the Device have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the Device will or will not be damaged by repairing.





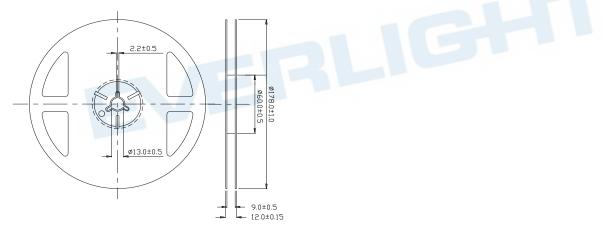
Taping Dimension

feeding direction



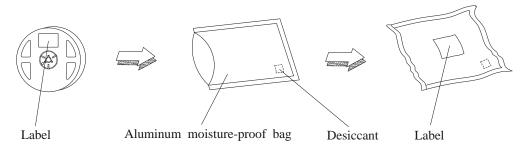
General Tolerance ±0.1 UNIT:mm

Reel Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

Moisture Resistant Packaging

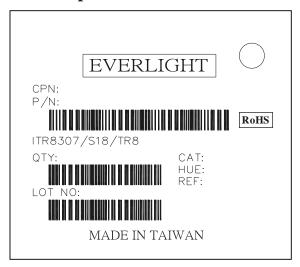




Packing Quantity Specification

- 1. 1000 Pcs/ 1Reel
- 2. 15 Reel / 1 Box
- 3. 2 Box / 1 Carton

Label Form Specification



CPN: Customer's Production Number

P/N : Production Number QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

MADE IN TAIWAN: Production Place

DISCLAIMER

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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